

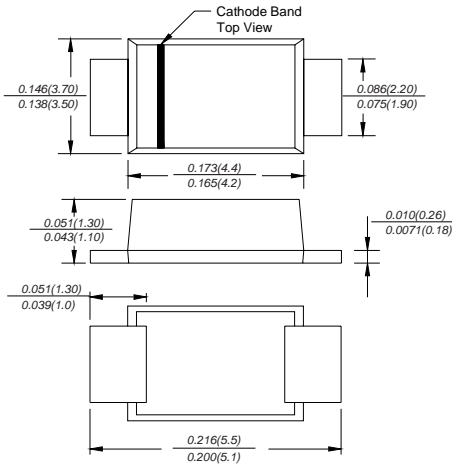


US2ABF THRU US2MBF

SURFACE MOUNT ULTRAFAST RECOVERY RECTIFIER

Reverse Voltage - 50 to 1000 Volts Forward Current - 2.0 Amperes

SMBF



FEATURES

- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Glass Passivated Chip Junction
- ◆ Easy to pick and place
- ◆ Superfast reverse recovery time
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

Case: JEDEC SMBF molded plastic body
Terminals: leads solderable per MIL-STD-750, Method 2026
Mounting Position: Any
Weight: 57mg/0.002oz

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

MDD Catalog Number	SYMBOLS	US2ABF	US2BBF	US2DBF	US2GBF	US2JBF	US2KBF	US2MBF	UNITS	
Marking code		U2AB	U2BB	U2DB	U2GB	U2JB	U2KB	U2MB		
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	VOLTS	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	VOLTS	
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	VOLTS	
Maximum average forward rectified current at $T_L=65^\circ\text{C}$	$I_{(AV)}$	2.0							Amps	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							Amps	
Maximum instantaneous forward voltage at 2.0A	V_F	1.0		1.3		1.6			Volts	
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	5.0 100.0							μA	
Maximum reverse recovery time (NOTE 1)	t_{rr}	50				75				ns
Typical junction capacitance (NOTE 2)	C_J	60							pF	
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ $R_{\theta JL}$	60 20							$^\circ\text{C/W}$	
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$	

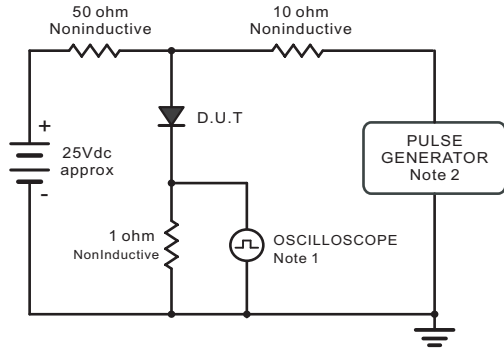
Note: 1. Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3. P.C.B. mounted with 0.5x0.5" (12.7x12.7mm) copper pad areas



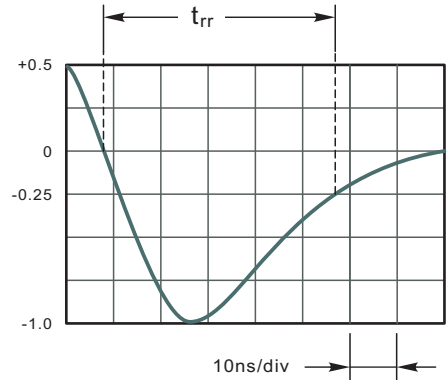
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RATINGS AND CHARACTERISTIC CURVES US2ABF THRU US2MBF

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1 megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

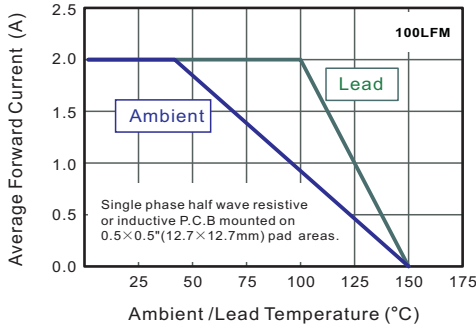


Fig.3 Typical Reverse Characteristics

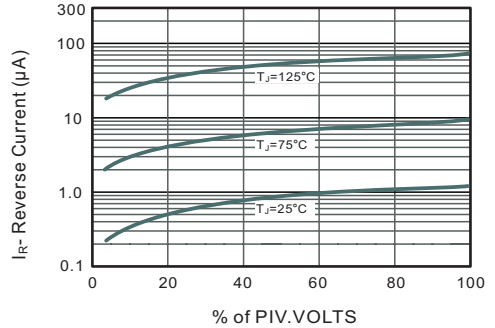


Fig.3 Typical Instaneous Forward Characteristics

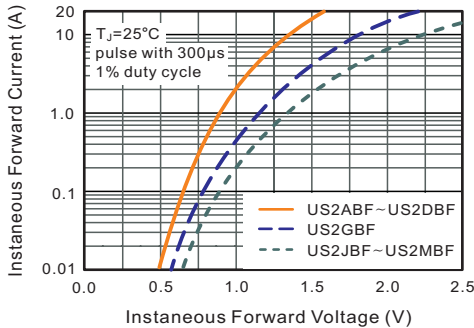
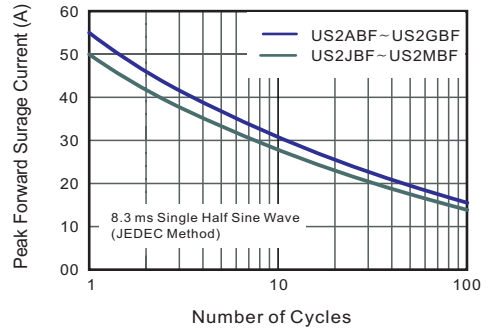


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current



The cruve graph is for reference only, can't be the basis for judgment(曲线图仅供参考)!



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